L Number	Hits	Search Text	DB	Time stamp
1	307097	heat with (sink spreader lid cover dissipate dissipation dissipated dissipated slug frame radiate radiating radiated)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 10:05
2	2581220	semiconductor die dice chip ic (integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 10:06
3	3734087	substrate board carrier pcb ((wiring printed circuit) adj "4" board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 10:07
4	106697	(thermally thermal) adj6 (isolated insulated insulation insulate insulating)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 11:41
5	390	(heat with (sink spreader lid cover dissipate dissipation dissipated dissipated slug frame radiate radiating radiated)) same (semiconductor die dice chip ic (integrated adj circuit)) same (substrate board carrier pcb ((wiring printed circuit) adj "4" board)) same ((thermally thermal) adj6 (isolated insulated insulation insulate insulating))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 11:41
6	5080	(thermally thermal) adj6 (isolated)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 11:41
7	390	(heat with (sink spreader lid cover dissipate dissipation dissipated dissipated slug frame radiate radiating radiated)) same (semiconductor die dice chip ic (integrated adj circuit)) same (substrate board carrier pcb ((wiring printed circuit) adj "4" board)) same ((heat with (sink spreader lid cover dissipate dissipation dissipated dissipated slug frame radiate radiating radiated)) same (semiconductor die dice chip ic (integrated adj circuit)) same (substrate board carrier pcb ((wiring printed circuit) adj "4" board)) same ((thermally thermal) adj6 (isolated insulated insulation insulate insulating)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 11:43

8	0	((heat with (sink spreader lid cover dissipate dissipation dissipated dissipated slug frame radiate radiating radiated)) same (semiconductor die dice chip ic (integrated adj circuit)) same (substrate board carrier pcb ((wiring printed circuit) adj "4" board)) same ((heat with (sink spreader lid cover dissipate dissipation dissipated dissipated slug frame radiate radiating radiated)) same (semiconductor die dice chip ic (integrated adj circuit)) same (substrate board carrier pcb ((wiring printed circuit) adj "4" board)) same ((thermally thermal) adj6 (isolated insulated insulation insulate insulating)))) not ((heat with (sink spreader lid cover dissipate dissipation dissipated dissipated slug frame radiate radiating radiated)) same (semiconductor die dice chip ic (integrated adj circuit)) same (substrate board carrier pcb ((wiring printed circuit) adj "4" board)) same ((thermally thermal) adj6 (isolated insulated insulation insulate insulating)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 11:42
10	0	((heat with (sink spreader lid cover dissipate dissipation dissipated dissipated slug frame radiate radiating radiated)) same (semiconductor die dice chip ic (integrated adj circuit)) same (substrate board carrier pcb ((wiring printed circuit) adj "4" board)) same ((thermally thermal) adj6 (isolated))) not ((heat with (sink spreader lid cover dissipate dissipation dissipated dissipated slug frame radiate radiating radiated)) same (semiconductor die dice chip ic (integrated adj circuit)) same (substrate board carrier pcb ((wiring printed circuit) adj "4" board)) same ((thermally thermal) adj6 (isolated insulated insulation insulate insulating)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 11:43
9	45	(heat with (sink spreader lid cover dissipate dissipation dissipated dissipated slug frame radiate radiating radiated)) same (semiconductor die dice chip ic (integrated adj circuit)) same (substrate board carrier pcb ((wiring printed circuit) adj "4" board)) same ((thermally thermal) adj6 (isolated))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 11:44
11	728	(heat with (sink spreader lid cover dissipate dissipation dissipated dissipated slug frame radiate radiating radiated)) and (semiconductor die dice chip ic (integrated adj circuit)) and (substrate board carrier pcb ((wiring printed circuit) adj "4" board)) and ((thermally thermal) adj6 (isolated))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 11:45

| 12 | 683 | ((heat with (sink spreader lid cover dissipate dissipation dissipated dissipated slug frame radiate radiating radiated)) and (semiconductor die dice chip ic (integrated adj circuit)) and (substrate board carrier pcb ((wiring printed circuit) adj "4" board)) and ((thermally thermal) adj6 (isolated))) not ((heat with (sink spreader lid cover dissipate dissipation dissipated dissipated slug frame radiate radiating radiated)) same (semiconductor die dice chip ic (integrated adj circuit)) same (substrate board carrier pcb ((wiring printed circuit) adj "4" board)) same ((thermally thermal) adj6 (isolated))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/30 11:45 |